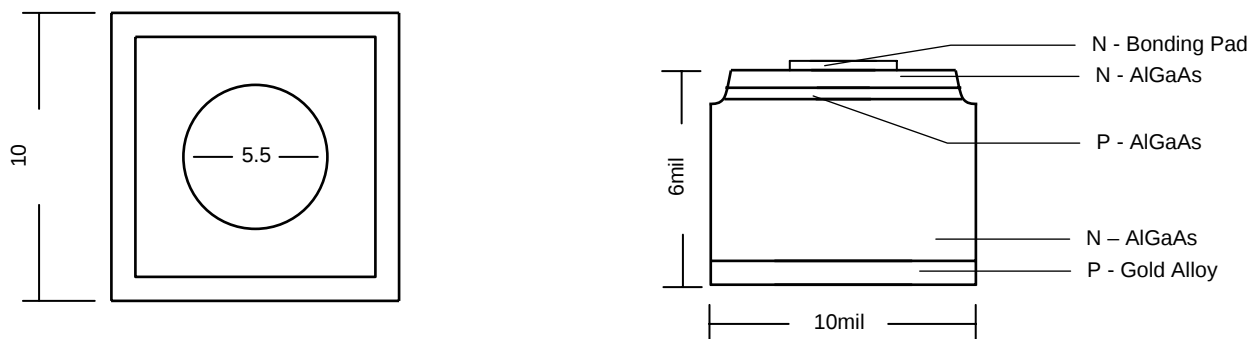


TCM730-5

❖ Outline Dimensions:



❖ Physical Structure:

Chip dimensions		Chip size	10 mil x 10 mil	260 μ m x 260 μ m
		Thickness	6 mil	150 μ m
		Bonding pad	5.5 mil	140 μ m
Electrode	Top	N (cathode)	Gold alloy	
	Backside	P (anode)	Gold alloy	

❖ Electro-Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 20\text{mA}$	-	1.50	1.90	V
Reverse Voltage	V_R	$I_R = 10\mu\text{A}$	5	-	-	V
Peak Wavelength	λ_P	$I_F = 20\text{mA}$	725	730	735	nm
Spectral Bandwidth	$\Delta\lambda$	$I_F = 20\text{mA}$	-	25	-	nm
Radiant Flux	P_O	$I_F = 20\text{mA}$	0.5	1.2	-	mW